

MODEL DM-812

Full-Automatic Die Attach Sheet Lamination System

Outline

The DM-812 is the ideal system for laminating die attach sheet.

Features

- Capable of handling 12" 150 μ thickness wafers and aligning precisely.
- Uniform lamination by using special heater and roller control system.
- After cure function inside, laminating wafer by wafer .
- Applicable for inlining with BG machine and wafer mounter. (optional)



Specification		DM-812
Throughput		25~30wafers/hour (Depend on data setting)
Wafer Size		8 · 12 inch
Tape Width		8 inch : W235~240mm 12 inch : W350~400mm
Utilities	Power	AC200V 3phase 50/60Hz 17KVA
	Air	Pressure 0.5Mpa 150NI/min
	Vacuum source	-74Kpa×2
Dimensions		D 3,030 × W 1,900 × H 1,800mm
Weight		950 kg

System appearance and specifications are subject to change without prior notice from the supplier.

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